

Title (en)

Floor panel

Title (de)

Bodenplatte

Title (fr)

Panneau de plancher

Publication

**EP 1801302 A2 20070627 (EN)**

Application

**EP 06425835 A 20061213**

Priority

IT BA20050047 A 20051220

Abstract (en)

The patent for invention of this application regards a panel developed for floor. The panel is formed by some supporting elements linked to each other and drowned inside every light isotropic material, thermal and acoustic insulating, and with a good mechanical resistance. The resistance of the whole system is established by the pre-compression of an outline of lightened steel, which is inside the panel, and it's obtained thanks to steel wires or staffs, put in tension and properly anchored to the tips of the outline. The panel is suitable to be used as a structural element in the construction of horizontal and/or inclined supporting elements for civil or industrial buildings.

IPC 8 full level

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CPC (source: EP)

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